

# IPC-HERMES-9852

**Version 1.4**  
**2022 - February**

**The Global Standard for  
Machine-to-Machine  
Communication in  
SMT Assembly**

Supersedes HERMES-9852, Version 1.3  
May 2021

*Developed by The Hermes Standard Initiative and  
approved by IPC*



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**IPC-HERMES-9852**

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- Show relationship to Design for Manufacturability (DFM) and Design for the Environment (DFE)
- Minimize time to market
- Contain simple (simplified) language
- Just include spec information
- Focus on end product performance
- Include a feedback system on use and problems for future improvement

### Standards Should Not:

- Inhibit innovation
- Increase time-to-market
- Keep people out
- Increase cycle time
- Tell you how to make something
- Contain anything that cannot be defended with data

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# **The Global Standard for Machine-to-Machine Communication in SMT Assembly**

Developed by The Hermes Standard initiative and approved by IPC

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Users of this publication are encouraged to participate in the development of future revisions.

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# Acknowledgment

Any document involving a complex technology draws material from a vast number of sources across many continents. While the principal members of The Hermes Standard Initiative are shown below, it is not possible to include all of those who assisted in the evolution of this standard. To each of them, the members of IPC extend their gratitude.

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Figure 7	Communication Sequence in Scenario U1a . . . . .	7	Figure 20	Connection, Handshake and Connection Loss Detection on Vertical Channel . . . . .	19
Figure 8	Communication Sequence in Scenario U1b . . . . .	8	Figure 21	Example for Connection Loss Detection With Featurecheckaliveresponse on Vertical Channel . . . . .	20
Figure 9	Communication sequence in Scenario U2 . . . . .	9	Figure 22	Hermes Interface States on Vertical Channel . . . . .	21
Figure 10	Communication Sequence in Scenario U3 . . . . .	10	Figure 23	Explanation for Top and Bottom Clearance Height . . . . .	26
Figure 11	Communication Sequence in Scenario D1 . . . . .	11	Figure 24	Line Setup With Barcode Readers and Repair Station . . . . .	43
Figure 12	Communication Sequence in Scenario D2 . . . . .	12	Figure 25	Line Setup With Fixed and Mobile Barcode Readers . . . . .	
Figure 13	Communication Sequence in Scenario D3 . . . . .	13	Figure 26	SMT Subline That Is Involved in Oven Error Loop . . . . .	45
Figure 14	Example of Communication Sequence for BoardForecast . . . . .	14	Figure 27	Example Subline Showing Use Case Request Pause / Confirm Pause and Resume Operation . . . . .	46
Figure 15	Example of Communication Sequence for Boardforecast With RevokeMachineReady . . . . .	14	Figure 28	Board Removal at Downstream Conveyor . . . . .	47
Figure 16	Example of Communication Sequence With Several BoardForecast . . . . .	15	Figure 29	Reversal Transportation, Downstream Flipping Unit . . . . .	47
Figure 17	Example of Communication Sequence in Case With Error Handling . . . . .	16	Figure 30	Reversal Transportation, Upstream Flipping Unit . . . . .	48
Figure 18	Example of Communication Sequence BoardForecast Without Product Change . . . . .	16	Figure 31	Board Routing, Predefined Routes . . . . .	49
Figure 19	Hermes Interface States on Horizontal Channel . . . . .	17	Figure 32	Board Routing, Multiple Target Locations . . . . .	50

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# The Global Standard for Machine-to-Machine Communication in SMT Assembly

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## 1 SCOPE

The aim of this specification is to create a state-of-the-art communication protocol for surface-mount technology (SMT) production lines. Therefore, this new communication protocol has to cope with the following:

- Replace the electrical SMEMA interface as specified in IPC-SMEMA-9851
- Extend the interface to communicate:
  - Unique identifiers for the handled printed circuit boards (PCBs)
  - Equipment identifiers of the first machine noticing a PCB
  - Barcodes
  - Conveyor speed
  - Product type specific information:
    - Product type identifier
    - Length
    - Width
    - Thickness
    - ...

With respect to version numbers The Hermes Standard adheres to the rules of Semantic Versioning 2.0.0 [SemVer\_2.0.0].

Hints on naming:

- Wherever a feature is described by the word “shall“ it is mandatory.
- The word “machine” is used for any equipment which can be found in a SMT production line (e.g., printers, placement machines, ovens, AOIs, transport modules, shuttles, stackers).
- The term “PCB” may also refer to carriers transporting PCBs.
- The word “Hermes” is used as abbreviation for “The Hermes Standard”.
- “The Hermes Standard” and IPC-HERMES-9852 are synonyms for the standard specified in this document and might be used interchangeably.